



**DIGITCONCEPT**

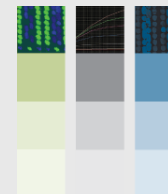
Microelectronics & HighTech Equipment

# *Nanoprobining at the 22nm and 16nm nodes*



## **Success Cultivates Success**

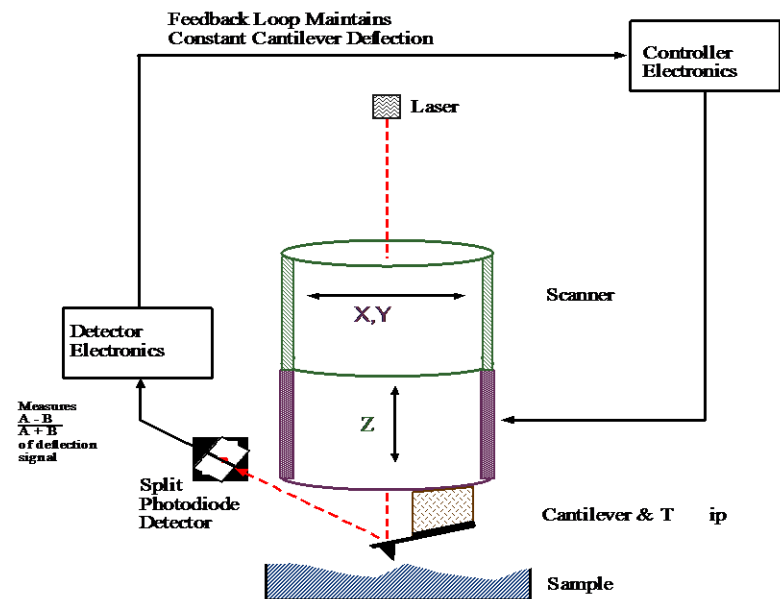
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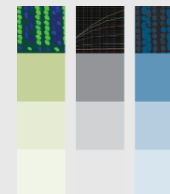
# Atomic Force Technology

- The AFP characterizes the electrical properties of an individual device using measured topography as an aid to probe placement.
- A constant tip-sample force is maintained throughout the measurement making the AFP non-destructive and easy to use.
- Why an AFM:
  - force feedback
  - non-destructive
  - non-contaminating
  - current imaging (PicoCurrent™)
  - scanning capacitance



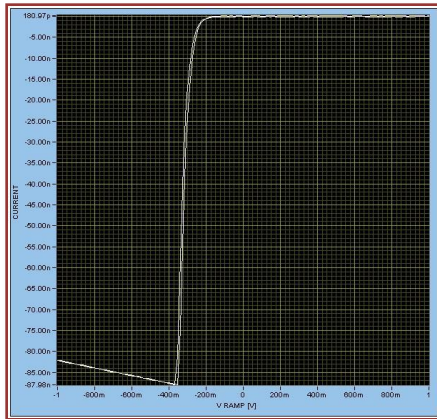
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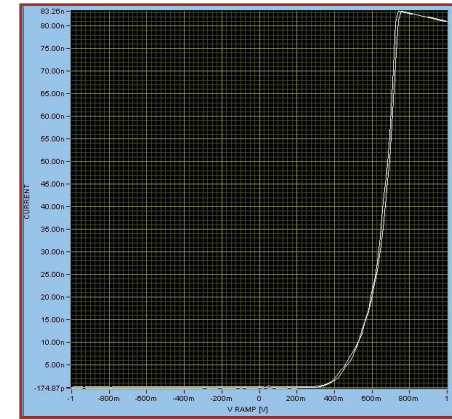
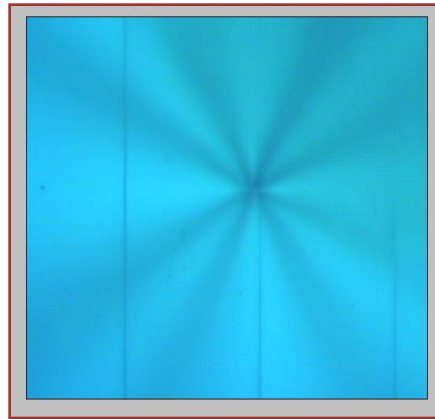


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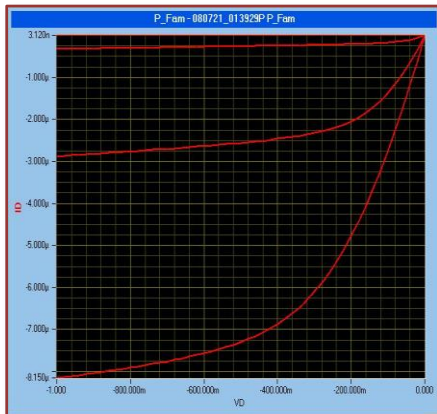
# DC Probing



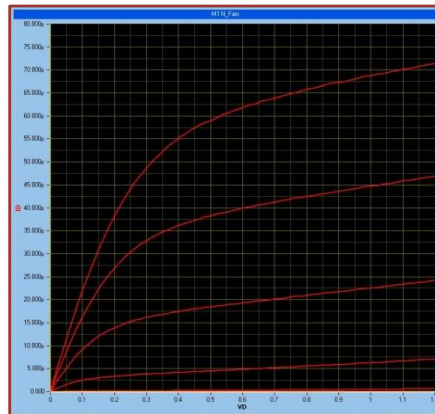
n-contact diode ramp



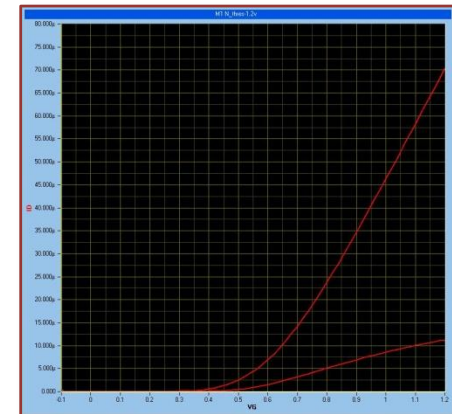
p-contact diode ramp



pull-up transistor



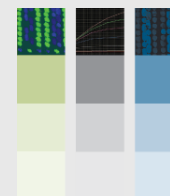
pull-down transistor



threshold voltage characteristics

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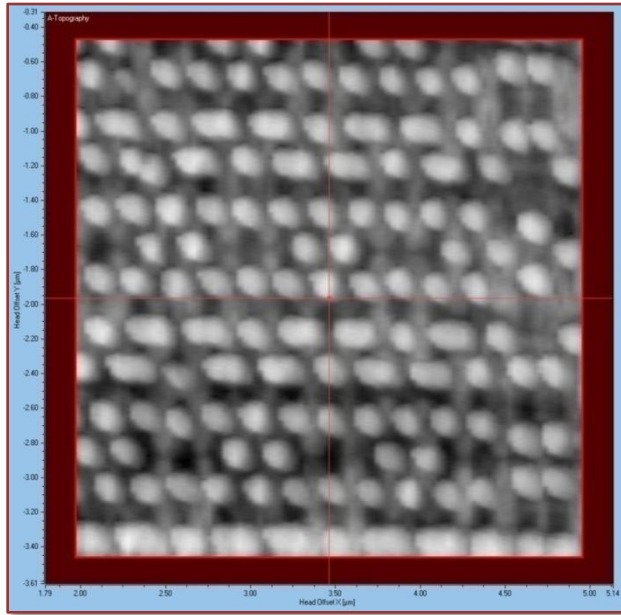
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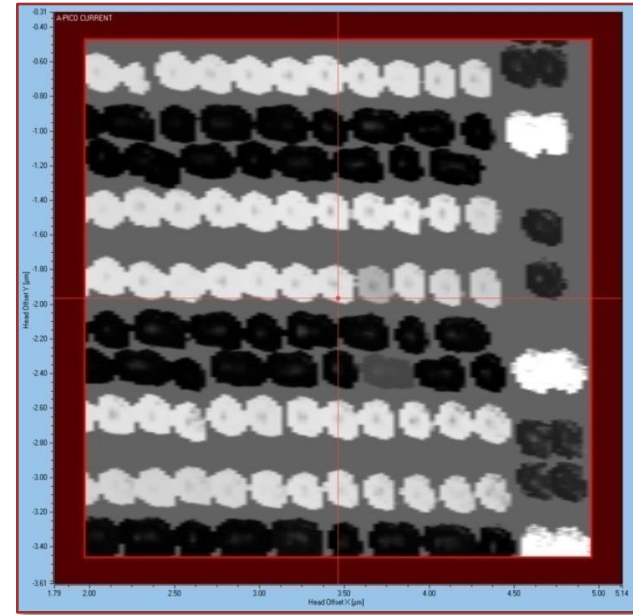
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# PicoCurrent (Fault localization)

- Find failures without the need to probe



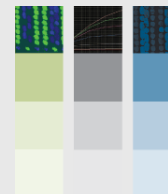
- Topography



- PicoCurrent

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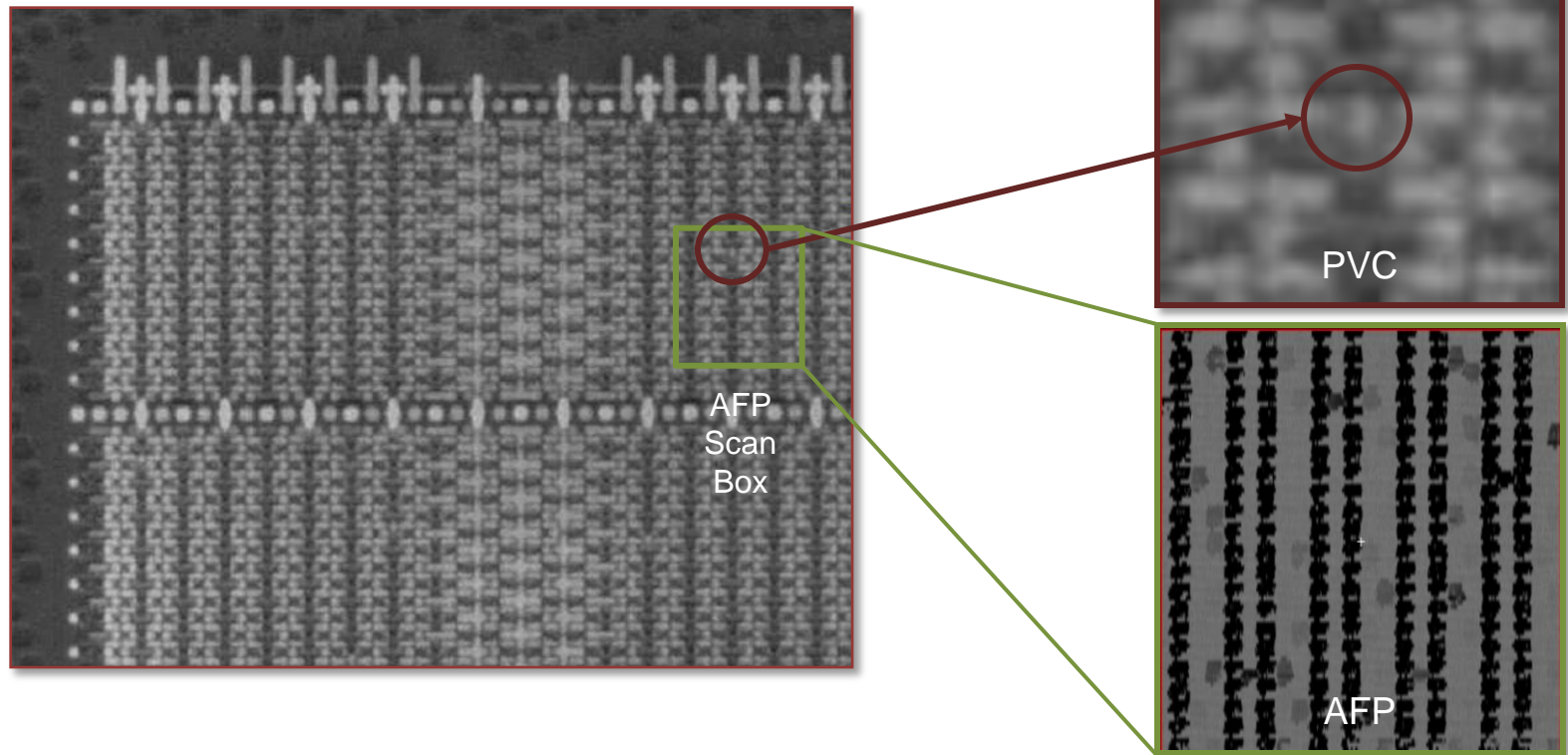
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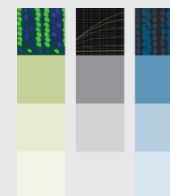
# PicoCurrent More Sensitive c.f. PVC

- eS35 Inspection of SRAM test structure



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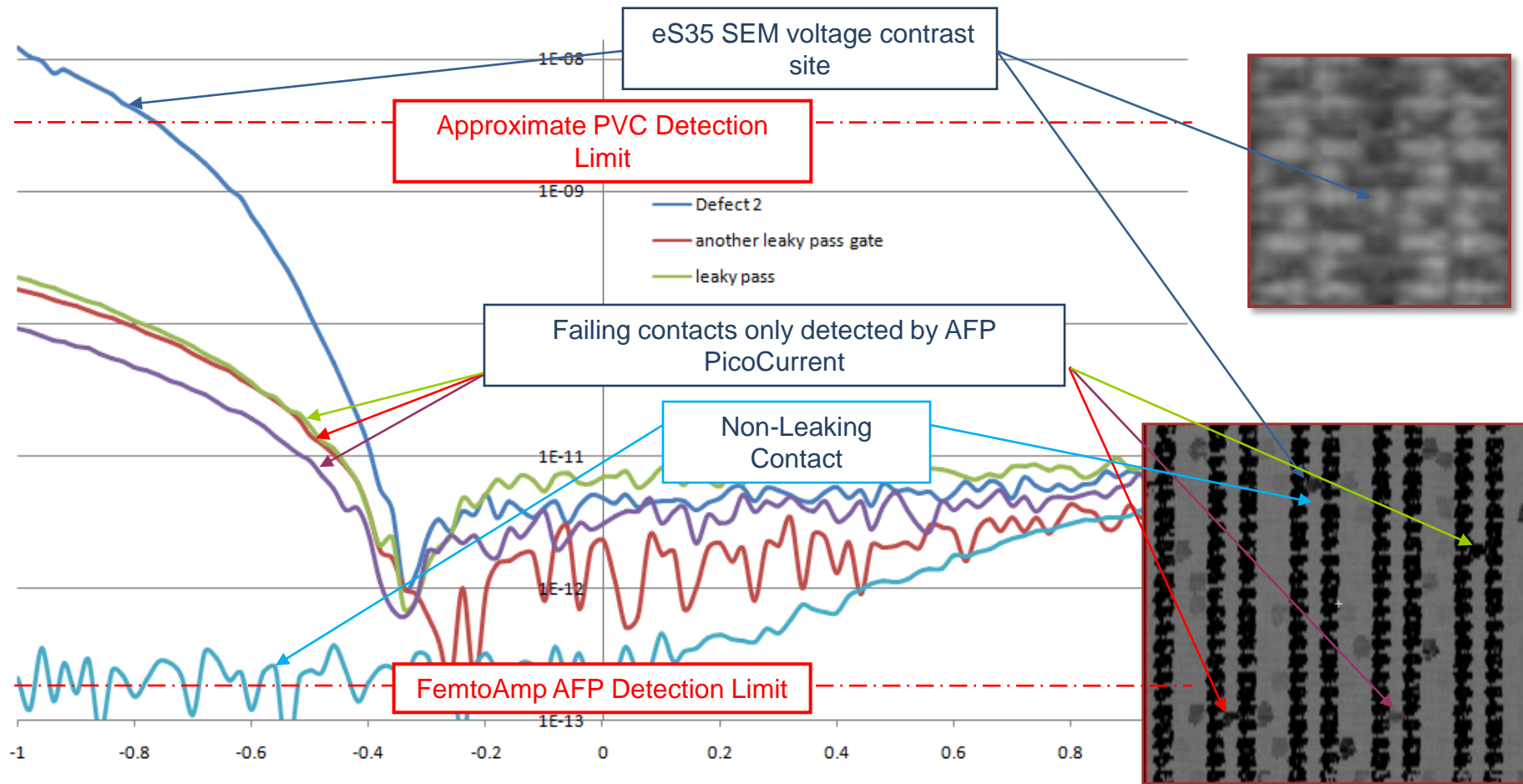
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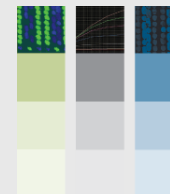


# AFP DC Measurements at Contact Post CMP



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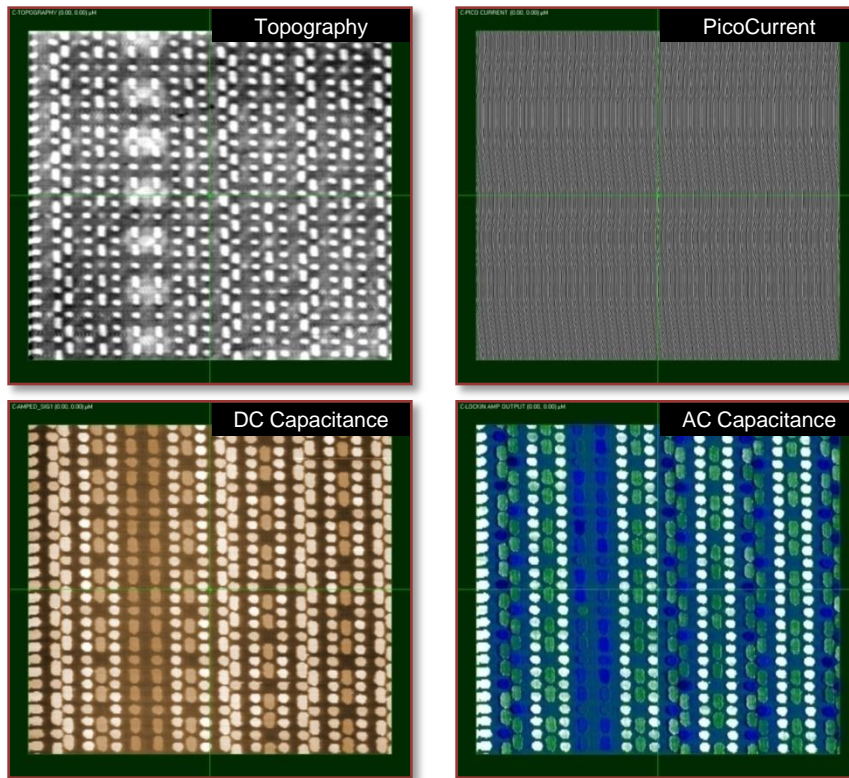
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# Current Imaging Is Not Applicable To SOI

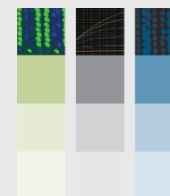
- The presence of a buried dielectric layer inhibits current flow



- The lack of PicoCurrent™ data with SOI devices makes localization of soft fails more difficult.
  - When used as a contrast mechanism, capacitance data brings back the ability to identify contacts.
- 
- Note the green contact in a sea of blue; a sure indication of a soft fail

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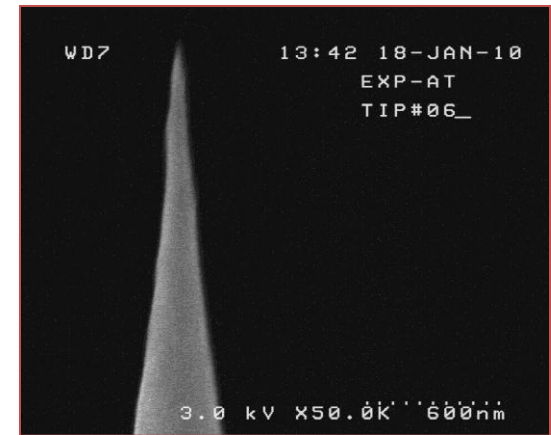
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# Roadmap to 16nm:

## High Sensitivity Levers, sharper tips

Mirrored levers have higher sensitivity

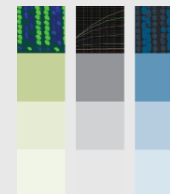
- 6mV/nm c.f. 1mV/nm with standard levers
- Better force control
  - Smaller reflected laser spot
    - 3x higher sensitivity
  - Shorter lever
    - 2x higher sensitivity



- Sharper than 45nm
- Conductive
- Contamination free

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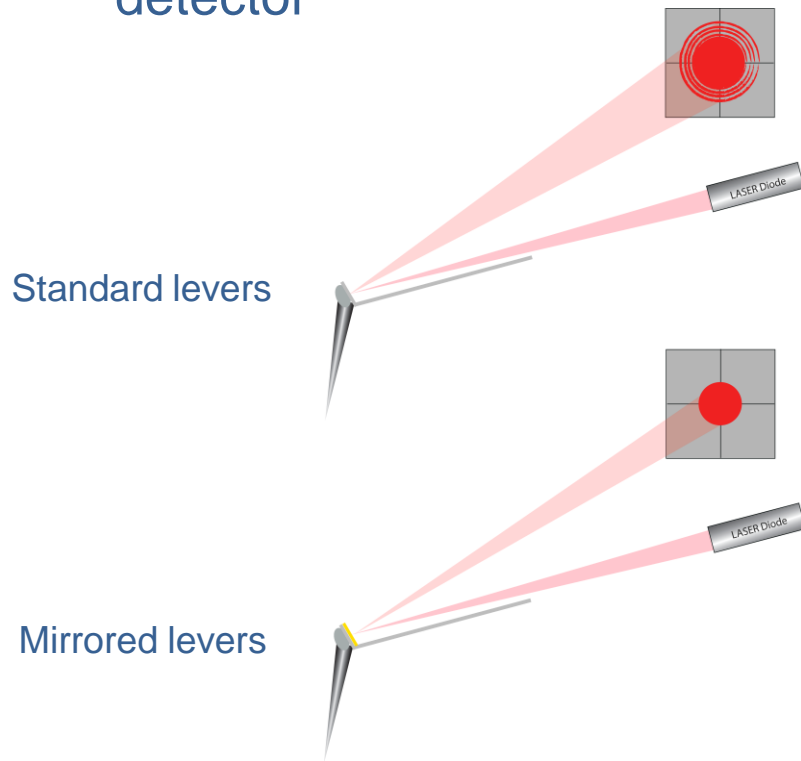


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# High Sensitivity Levers

Smaller reflected LASER spot at the photo-detector

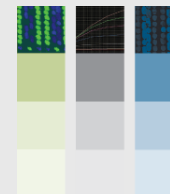


Mirrored levers have:

- Lower non-specula reflections
- Lower optical interference
- Higher lever sensitivity

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# Issues When Using High-Sensitivity Levers

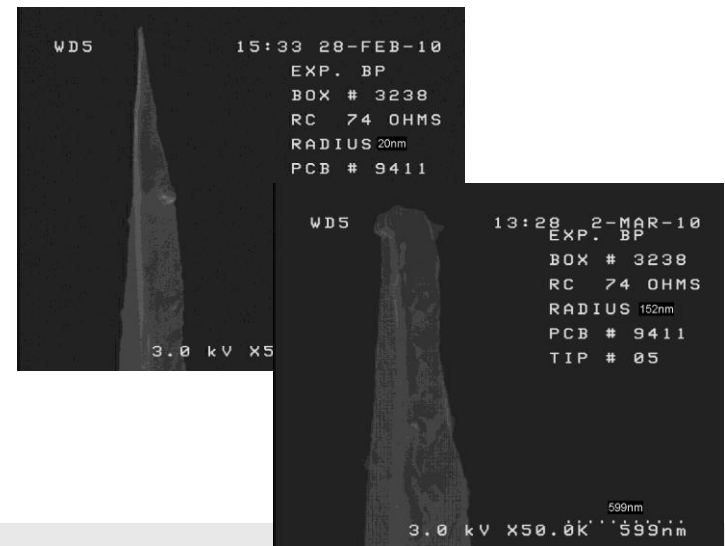
The high-sensitivity levers reveal the limits of the current MPII design

- Observations

- Cantilever goes into resonance
- No stable imaging
  - excessive force
  - tip/sample damage

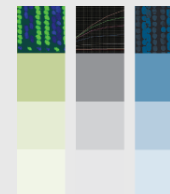
- MPII does not support the feedback bandwidth required for the preservation of “Ultra-Sharp” probes

- System Noise Too High



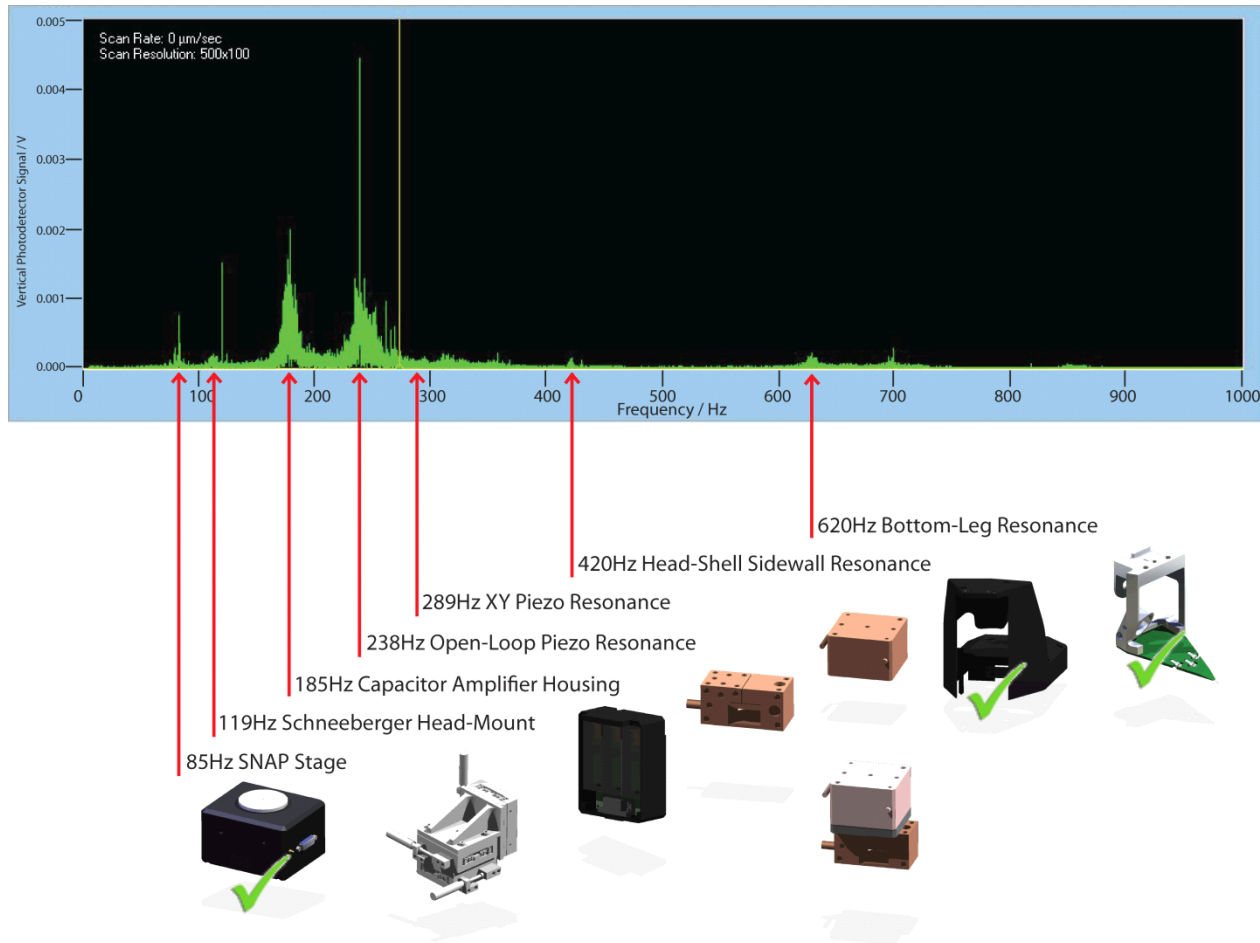
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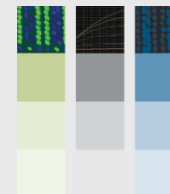
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# MPII Noise Spectrum



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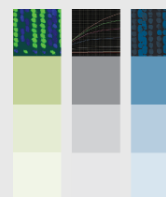
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# MPII vs. MPIIb

	MPII	MPIIb
Maximum number of heads	6	
XY scan range	24um	
XY positional accuracy	5nm	
Electrical resolution	<1p A	
Imaging modes	Topography, Pico Current, Scanning Capacitance	
Smallest accessible technology node	<32nm	16nm (22nm demonstrated)
Topographical resolution (Z)	5nm	2nm
Lever Sensitivity (typical)	1mV/nm	6mV/nm
Settling time after installing probes (typical)	2hrs	15min
Imaging force (typical)	0.24uN	0.025uN
Probe life (typical at 32nm node)	25 images + probing	150 images + probing
Stability	> 10min IV curve on 32nm	>10min IV curve on 22nm
Compatible probe types	AFP-065, AFP-045	AFP-065, AFP-045, AFP-035M

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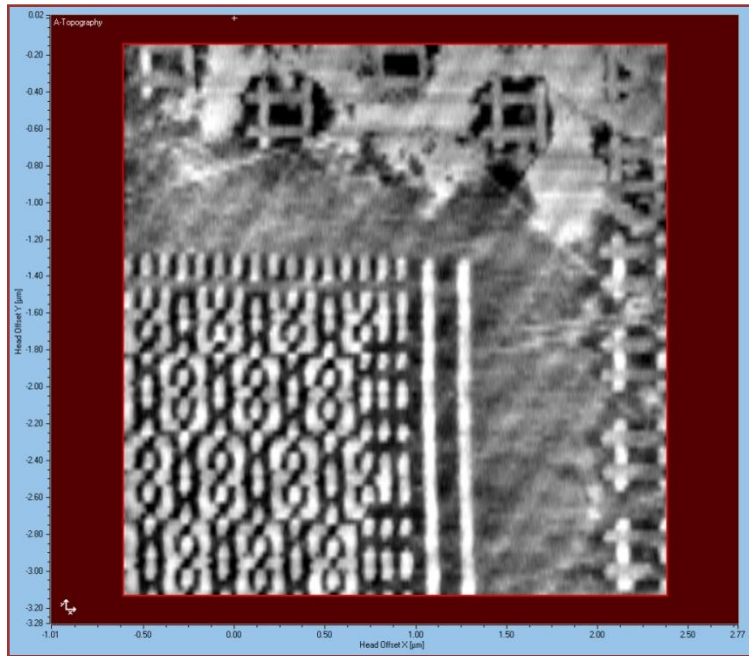
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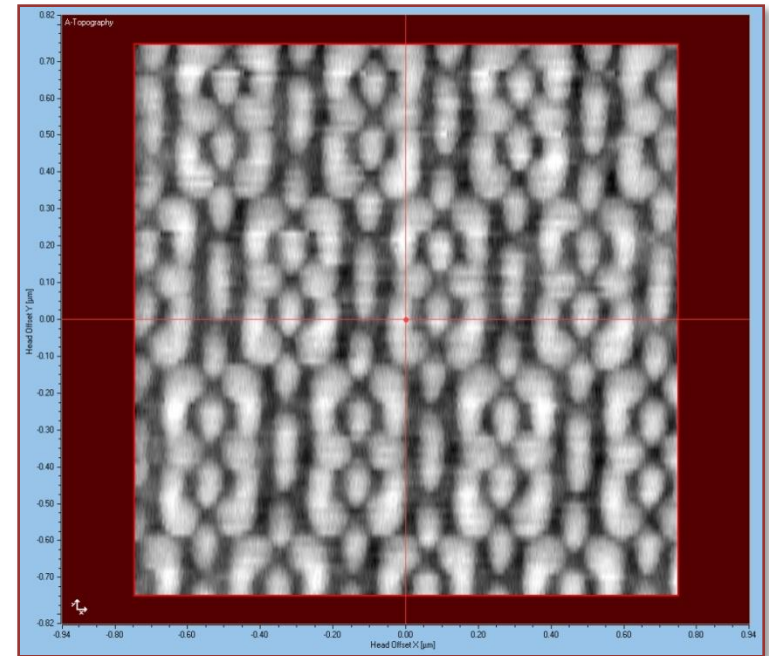
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# 22nm Topography

MPII vs. MPIIb



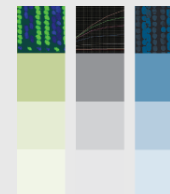
MPII



MPIIb

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